



DATASHEET

MGBIC-02-C

Product specifications



MGBIC-02-C

1000BASE-T copper SFP Transceiver

Product Features

- ✓ Up to 1.25Gb/s bi-directional data links
- ✓ Hot-pluggable SFP footprint
- ✓ Extended case temperature range (-5°C to +85°C)
- ✓ Fully metallic enclosure for low EMI
- ✓ Low power dissipation (1.05W typical)
- ✓ Compact RJ-45 connector assembly
- ✓ Access to physical layer IC via 2-wire serial bus
- ✓ 1000 BASE-T operation in host systems with SERDES interface
- ✓ 10/100/1000Mbps compliant in host systems with SGMII interface

Applications

- ✓ 1Gigabit Ethernet over Cat 5 cable

SFP to Host Connector Pin Out

PIN	Symbol	Name/Description	Ref.
1	VeeT	Transmitter ground (common with receiver ground)	1
2	TFAULT	Transmitter Fault. Not supported	
3	TDIS	Transmitter Disable. PHY disabled on high or open.	2
4	MOD_DEF(2)	Module Definition 2. Data line for serial ID	3
5	MOD_DEF(1)	Module Definition 1. Clock line for serial ID	3
6	MOD_DEF(0)	Module Definition 0. Grounded within the module.	3
7	Rate Select	No connection required	
8	LOS	Loss of Signal indication	4
9	VeeR	Receiver ground (common with transmitter ground)	1
10	VeeR	Receiver ground (common with transmitter ground)	1
11	VeeR	Receiver ground (common with transmitter ground)	1
12	RD-	Receiver Inverted DATA out. AC coupled	
13	RD+	Receiver Non-inverted DATA out. AC coupled	
14	VeeR	Receiver ground (common with transmitter ground)	1
15	VccR	Receiver Power Supply	
16	VccT	Transmitter power supply	
17	VeeT	Transmitter ground (common with receiver ground)	1
18	TD+	Transmitter Non-Inverted DATA in. AC coupled	
19	TD-	Transmitter Inverted DATA in. AC coupled	
20	VeeT	Transmitter ground (common with receiver ground)	1

Notes:

1. Circuit ground is connected to chassis ground
2. PHY disabled on TDIS > 2.0V or open, enabled on TDIS < 0.8V
3. Should be pulled up with 4.7k – 10k Ohms on host board to a voltage between 2.0 V and 3.6V. MOD_DEF(0) pulls line low to indicate module is plugged in.
4. LVTTTL compatible with a maximum voltage of 2.5V. Not supported on GE-GB-P.

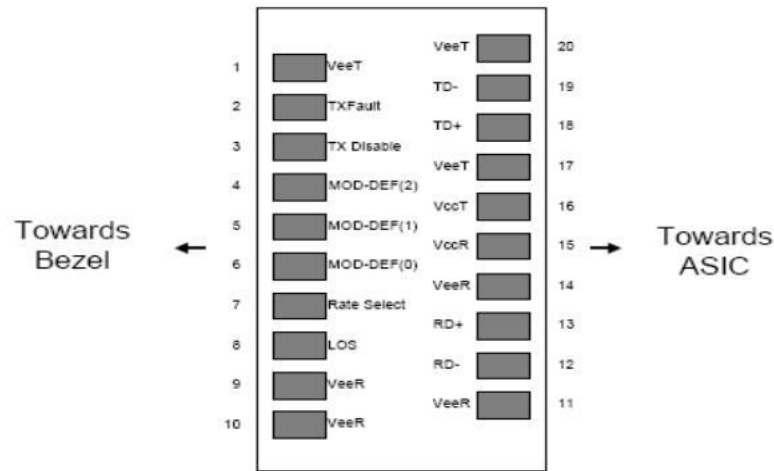


Figure 1. Diagram of host board connector block pin numbers and names

Table 1. SFP to host connector pin assignments and descriptions

+3.3V Volt Electrical Power Interface

The GE-GB-P has an input voltage range of 3.3 V +/- 5%. The 4 V maximum voltage is not allowed for continuous operation.

+3.3 Volt Electrical Power Interface						
Parameter	Symbol	Min	Typ	Max	Units	Notes/Conditions
Supply Current	I _s		320	375	mA	1.2W max power over full range of voltage and temperature See caution note below
Input Voltage	V _{cc}	3.13	3.3	3.47	V	Referenced to GND
Maximum Voltage	V _{max}			4	V	
Surge Current	I _{surge}			30	mA	Hot plug above steady state current. See caution note below

Caution: Power consumption and surge current are higher than the specified values in the SFP MSA

Table 2. +3.3 Volt electrical power interface

Low-Speed Signals

MOD_DEF(1) (SCL) and MOD_DEF(2) (SDA), are open drain CMOS signals (see section VII, “Serial Communication Protocol”). Both MOD_DEF(1) and MOD_DEF(2) must be pulled up to host_Vcc.

Low-Speed Signals, Electronic Characteristics					
Parameter	Symbol	Min	Max	Units	Notes/Conditions
SFP Output LOW	VOL	0	0.5	V	4.7k to 10k pull-up to host_Vcc, measured at host side of connector
SFP Output HIGH	VOH	host_Vcc - 0.5	host_Vcc + 0.3	V	4.7k to 10k pull-up to host_Vcc, measured at host side of connector
SFP Input LOW	VIL	0	0.8	V	4.7k to 10k pull-up to Vcc, measured at SFP side of connector
SFP Input HIGH	VIH	2	Vcc + 0.3	V	4.7k to 10k pull-up to Vcc, measured at SFP side of connector

Table 3. Low-speed signals, electronic characteristics

High-Speed Electrical Interface

All high-speed signals are AC-coupled internally.

High-Speed Electrical Interface, Transmission Line-SFP						
Parameter	Symbol	Min	Typ	Max	Units	Notes/Conditions
Line Frequency	fL		125		MHz	5-level encoding, per IEEE 802.3
Tx Output Impedance	Zout, TX		100		Ohm	Differential, for all Frequencies between 1MHz and 125MHz
Rx Input Impedance	Zin, RX		100		Ohm	Differential, for all Frequencies between 1MHz and 125MHz

Table 4. High-speed electrical interface, transmission line-SFP

High-Speed Electrical Interface

Host-SFP						
Parameter	Symbol	Min	Typ	Max	Units	Notes/Conditions
Single ended data input swing	Vinsing	250		1200	mV	Single ended
Single ended data output swing	Voutsing	350		800	mV	Single ended
Rise/Fall Time	Tr,Tf		175		psec	20%-80%
Tx Input Impedance	Zin		50		Ohm	Single ended
Rx Output Impedance	Zout		50		Ohm	Single ended

Table 5. High-speed electrical interface, host-SFP

General Specifications

General						
Parameter	Symbol	Min	Typ	Max	Units	Notes/Conditions
Data Rate	BR	10		1000	Mb/sec	IEEE 802.3 compatible. See Notes 2 through 4 below
Cable Length	L			100	m	Category 5 UTP. BER <10 ⁻¹²

Table 6. General specifications

Notes:

1. Clock tolerance is +/- 50 ppm
2. By default, the GE-GB-P is a full duplex device in preferred master mode
3. Automatic crossover detection is enabled. External crossover cable is not required
4. 1000 BASE-T operation requires the host system to have an SGMII interface with no clocks, and the module PHY to be configured per Application Note AN-2036. With a SERDES that does not support SGMII, the module will operate at 1000BASE-T only.

Environmental Specifications

The MGBIC-02-C has an extended range from 0°C to +85°C case temperature as specified in Table 8.

Environmental Specifications						
Parameter	Symbol	Min	Typ	Max	Units	Notes/Conditions
Operating Temperature	Top	-5		85	°C	Case temperature
Storage Temperature	Tsto	-40		85	°C	Ambient temperature

Table 7. Environmental specifications

